

# Linux Interface Specification DMAC

User's Manual: Software

RZ/G2L Group, RZ/V2L Group, RZ/V2N Group,  
RZ/G3E Group and RZ/Five

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## General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

### 1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

### 2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

### 3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

### 4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

### 5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

### 6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between  $V_{IL}$  (Max.) and  $V_{IH}$  (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between  $V_{IL}$  (Max.) and  $V_{IH}$  (Min.).

### 7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

### 8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

# How to Use This Manual

## 1. Purpose and Target Readers

This manual is designed to provide the user with an understanding of the hardware functions and electrical characteristics of the MPU. It is intended for users designing application systems incorporating the MPU.. It is intended for users developing software incorporating the processors. A basic knowledge of software development and Linux systems is necessary in order to use this document.

Particular attention should be paid to the precautionary notes when using the manual. These notes occur within the body of the text, at the end of each section, and in the Usage Notes section.

The revision history summarizes the locations of revisions and additions. It does not list all revisions. Refer to the text of the manual for details.

The following documents apply to the RZ/G2L Group, RZ/V2L Group, RZ/V2N Group, RZ/G3E Group and RZ/Five Group. Make sure to refer to the latest versions of these documents. The newest versions of the documents listed may be obtained from the Renesas Electronics Web site.

Document Type	Description	Document Title	Document No.
User's manual for Hardware	Hardware specifications (pin assignments, memory maps, peripheral function specifications, electrical characteristics, timing charts) and operation description  Note: Refer to the application notes for details on using peripheral functions.	RZ/G2L Group User's Manual: Hardware	---
		RZ/V2L Group User's Manual: Hardware	---
		RZ/Five Group User's Manual: Hardware	---
		RZ/V2N Group User's Manual: Hardware	---
		RZ/G3E Group User's Manual: Hardware	---
User's manual for Software	Description of DMAC Linux interface Specification	Linux interface Specification Device Driver DMAC	This user's manual
Application Note	Information on using peripheral functions and application examples Sample programs Information on writing programs in assembly language and C	Available from Renesas Electronics Web site.	
Renesas Technical Update	Product specifications, updates on documents, etc.		

2. Notation of Numbers and Symbols

3. Register Notation

#### 4. List of Abbreviations and Acronyms

Abbreviation	Full Form
DMA	Direct Memory Access
DMAC	Direct Memory Access Controller

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# 1. Overview

## 1.1 Overview

This manual explains the DMA Engine device driver in Linux Solution for RZ/G2L Group, RZ/V2L Group, RZ/Five, RZ/V2N Group and RZ/G3E Group.

Note: Currently, this device is supported in two kernel versions v5.10 and v6.1 with the information below:

- v5.10: RZ/G2L Group, RZ/V2L Group and RZ/Five Group.
- v6.1: RZ/G2L, RZ/G2LC, RZ/V2N Group and RZ/G3E Group.

## 1.2 DMAC HW support

**Table 1-1 Support DMAC in RZ/G2L Group, RZ/V2L Group and RZ/Five**

	RZ/G2L group, RZ/V2L Group, and RZ/Five
SYS-DMAC	16 channels

**Table 1-2 Support DMAC in RZ/V2N Group and RZ/G3E Group**

	RZ/V2N Group and RZ/G3E Group
SYS-DMAC	5 DMAC modules, each has 16 channels

## 1.3 Function

This module controls DMAC by using DMA Engine framework and provides the following functions:

- DMA device driver module management with DMA Engine framework.
- Control each channel of support DMAC. (Refer to **Table 1-1** and **Table 1-2** in details)
- Call the registered callback function when DMA transfer is completed.
- Control the data transfer between the memory and the peripheral (such as SSI, RSPI, SCIF...), memory to memory. (SYS-DMAC)
- Forced to terminate during transmission.
- Control the descriptor transfer.

## 1.4 Restrictions

There is no restriction in this module.



## 2. Terminology

The following table shows the terminology related to this module.

**Table 2-1 Terminology**

Terms	Explanation
DMA	Direct Memory Access
DMAC	DMA Controller
SYS-DMAC	System DMAC

### 3. Operating Environment

#### 3.1 Module Configuration

The following figure shows the configuration of this module.

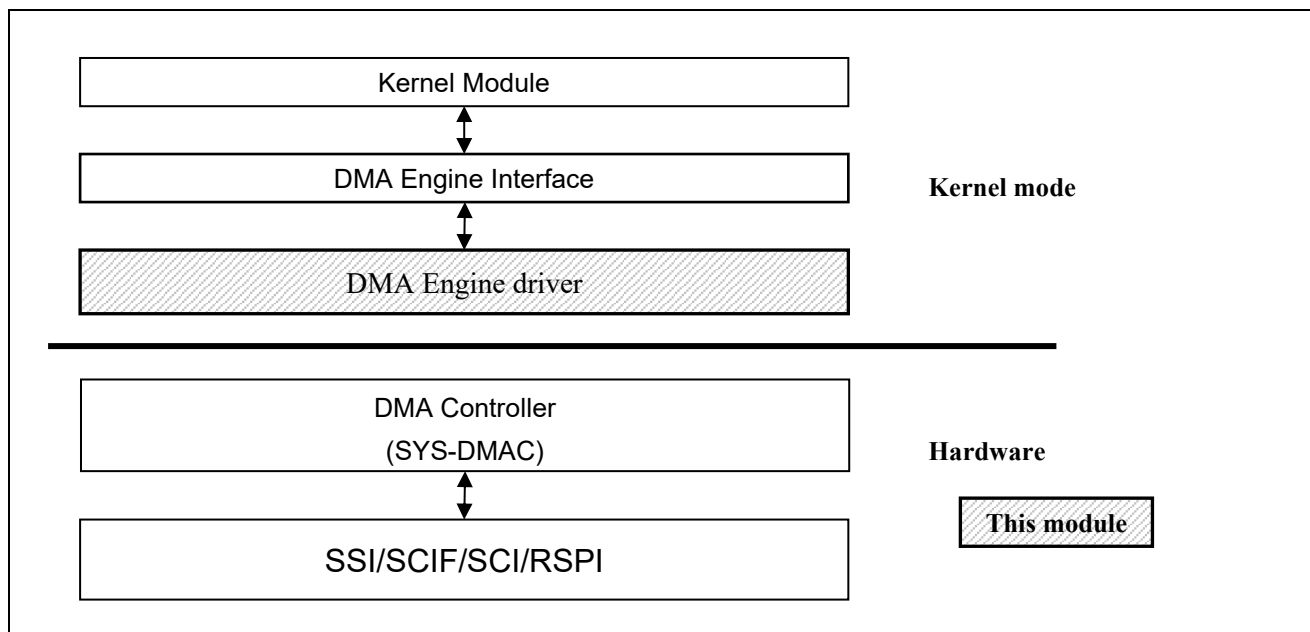


Figure 3-1 DMA Engine Driver configuration

#### 3.2 State Transition Diagram

The state transition managed by this module has "DMA stop" state and "During DMA transmission" state. This module does not support the suspend state.

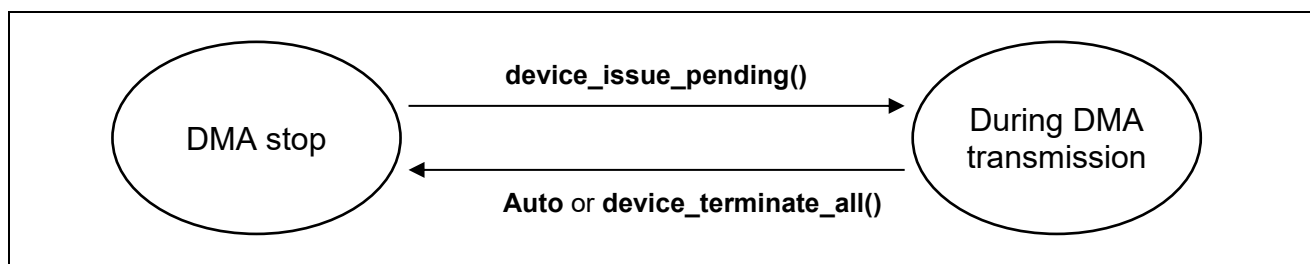


Figure 3-2 DMA Engine Driver State Transition Diagram RZ/G2L Group, RZ/V2L, RZ/Five, RZ/V2N and RZ/G3E

## 4. Integration

### 4.1 Hardware Environment

The following table lists the hardware needed to use this module.

**Table 4-1 Hardware specification for RZ/G2L, RZ/2LC, RZ/G2UL, RZ/V2L, and RZ/Five**

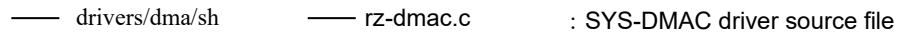
Name	Version	Manufacture
RZ/G2L Evaluation Board Kit	SMARC module: v01 Carrier board: v03	Renesas Electronics Europe GmbH
RZ/G2LC Evaluation Board Kit	SMARC module: v01 Carrier board: v03	Renesas Electronics Europe GmbH
RZ/G2UL Evaluation Board Kit	SMARC module: v01 Carrier board: v03	Renesas Electronics Europe GmbH
RZ/V2L Evaluation Board Kit	SMARC module: v01 Carrier board: v03	Renesas Electronics Europe GmbH
RZ/Five Evaluation Board Kit	SMARC module: v01 Carrier board: v03	Renesas Electronics Europe GmbH

**Table 4-2 Hardware specification for RZ/V2N and RZ/G3E**

Name	Product number
RZ/V2N Evaluation Kit	RTK0EF0186C03000BJ
RZ/G3E SMARC Evaluation Board Kit	RTK9947E57S01000BE

## 4.2 Directory Configuration

The directory configuration is shown below.

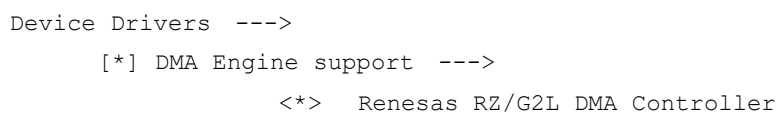
A diagram showing the directory structure for the SYS-DMAC driver. It consists of two horizontal lines. The first line is labeled 'drivers/dma/sh' and the second line is labeled 'rz-dmac.c'. To the right of these lines, there is a text label ': SYS-DMAC driver source file'.

```
—— drivers/dma/sh      —— rz-dmac.c      : SYS-DMAC driver source file
```

**Figure 4–1 Directory configuration**

## 4.3 Integration Procedure

To enable the function of this module, make the following setting with Kernel Configuration.

A screenshot of the Kernel Configuration menu. It shows a hierarchical structure with 'Device Drivers' expanded, 'DMA Engine support' selected, and 'Renesas RZ/G2L DMA Controller' highlighted.

```
Device Drivers --->
  [*] DMA Engine support --->
    <*> Renesas RZ/G2L DMA Controller
```

**Figure 4–2 Kernel configuration**

## 5. Device Tree Setting

### 5.1 DMA node

Basic configuration information of SYS-DMAC is defined at device tree file (r9a07g044.dtsi for RZ/G2L, RZ/G2LC, r9a07g043.dtsi RZ/G2UL, RZ/Five or r9a07g054.dtsi for RZ/V2L, r9a09g056.dtsi for RZ/V2N, r9a09g047.dtsi for RZ/G3E). It exists at arch/arm64/boot/dts/renesas directory. This module uses these described contents in the device tree file.

#### 5.1.1 On RZ/G2L, RZ/G2LC, RZ/G2UL, RZ/V2L, and RZ/Five

Figure 5–1 shows details about the initial reference information for DMAC node of RZ/G2L, RZ/G2LC, and RZ/V2L.

```

dma-controller@11820000 {
    compatible = "renesas,r9a07g044-dmac",
                 "renesas,rz-dmac";
    reg = <0 0x11820000 0 0x10000>,
          <0 0x11830000 0 0x10000>;
    interrupts = <GIC_SPI 141 IRQ_TYPE_EDGE_RISING>,
                 <GIC_SPI 125 IRQ_TYPE_EDGE_RISING>,
                 <GIC_SPI 126 IRQ_TYPE_EDGE_RISING>,
                 <GIC_SPI 127 IRQ_TYPE_EDGE_RISING>,
                 <GIC_SPI 128 IRQ_TYPE_EDGE_RISING>,
                 <GIC_SPI 129 IRQ_TYPE_EDGE_RISING>,
                 <GIC_SPI 130 IRQ_TYPE_EDGE_RISING>,
                 <GIC_SPI 131 IRQ_TYPE_EDGE_RISING>,
                 <GIC_SPI 132 IRQ_TYPE_EDGE_RISING>,
                 <GIC_SPI 133 IRQ_TYPE_EDGE_RISING>,
                 <GIC_SPI 134 IRQ_TYPE_EDGE_RISING>,
                 <GIC_SPI 135 IRQ_TYPE_EDGE_RISING>,
                 <GIC_SPI 136 IRQ_TYPE_EDGE_RISING>,
                 <GIC_SPI 137 IRQ_TYPE_EDGE_RISING>,
                 <GIC_SPI 138 IRQ_TYPE_EDGE_RISING>,
                 <GIC_SPI 139 IRQ_TYPE_EDGE_RISING>,
                 <GIC_SPI 140 IRQ_TYPE_EDGE_RISING>;
    interrupt-names = "error",
                     "ch0", "ch1", "ch2", "ch3",
                     "ch4", "ch5", "ch6", "ch7",
                     "ch8", "ch9", "ch10", "ch11",
                     "ch12", "ch13", "ch14", "ch15";
    clocks = <&cpg CPG_MOD R9A07G044_DMAC_ACLK>,
            <&cpg CPG_MOD R9A07G044_DMAC_PCLK>;
    clock-names = "main", "register";
    power-domains = <&cpg>;
    resets = <&cpg R9A07G044_DMAC_ARESETN>,
            <&cpg R9A07G044_DMAC_RST_ASYNC>;
    reset-names = "arst", "rst_async";
    #dma-cells = <1>;
    dma-channels = <16>;
};

```

Figure 5–1 Device tree initial references information of DMAC (RZ/G2L, RZ/G2LC and RZ/V2L)

Note: All of the information in the above device tree is used for both RZ/G2L, RZ/G2LC and RZ/V2L except: clocks and resets.

Required properties:

- **compatible:**  
must be “renesas, r9a07g044-dmac” for R9A07G044L, R9A07G044C (RZ/G2L, RZ/G2LC), “renesas, r9a07g043-dmac” for R9A07G043 (RZ/G2UL), and “renesas, r9a07g054-dmac” for R9A07G054 (RZ/V2L),
- **reg:**  
need two resources, first one mapped to register base address, second one mapped to extension resource registers base address.
- **interrupts:**  
interrupt specifier for the DMAC, one for each channel.
- **interrupt-names:**  
mapped with interrupts and must be in format: “ch%u” (%u: channel number 0->15), “error”.
- **dma-channels:**  
number of dma channel. Maximum is 16.
- **#dma-cells:**  
must be 1.
- **clocks, resets:** CPG\_MOD R9A07G044\_DMAC\_X is used for RZ/G2L, RZ/G2LC, CPG\_MOD R9A07G043\_DMAC\_X is used for RZ/G2UL, RZ/Five, and CPG\_MOD R9A07G054\_DMAC\_X is used for RZ/V2L.  
phandle + clock/reset specifier pairs.

- RZ/Five: DMA node: arch/arm64/boot/dts/renesas/r9a07g043.dtsi

```

dmac: dma-controller@11820000 {
    compatible = "renesas,r9a07g043-dmac",
                 "renesas,rz-dmac";
    reg = <0 0x11820000 0 0x10000>,
          <0 0x11830000 0 0x10000>;
    interrupts = <SOC_PERIPHERAL_IRQ(141) IRQ_TYPE_EDGE_RISING>,
                 <SOC_PERIPHERAL_IRQ(125) IRQ_TYPE_EDGE_RISING>,
                 <SOC_PERIPHERAL_IRQ(126) IRQ_TYPE_EDGE_RISING>,
                 <SOC_PERIPHERAL_IRQ(127) IRQ_TYPE_EDGE_RISING>,
                 <SOC_PERIPHERAL_IRQ(128) IRQ_TYPE_EDGE_RISING>,
                 <SOC_PERIPHERAL_IRQ(129) IRQ_TYPE_EDGE_RISING>,
                 <SOC_PERIPHERAL_IRQ(130) IRQ_TYPE_EDGE_RISING>,
                 <SOC_PERIPHERAL_IRQ(131) IRQ_TYPE_EDGE_RISING>,
                 <SOC_PERIPHERAL_IRQ(132) IRQ_TYPE_EDGE_RISING>,
                 <SOC_PERIPHERAL_IRQ(133) IRQ_TYPE_EDGE_RISING>,
                 <SOC_PERIPHERAL_IRQ(134) IRQ_TYPE_EDGE_RISING>,
                 <SOC_PERIPHERAL_IRQ(135) IRQ_TYPE_EDGE_RISING>,
                 <SOC_PERIPHERAL_IRQ(136) IRQ_TYPE_EDGE_RISING>,
                 <SOC_PERIPHERAL_IRQ(137) IRQ_TYPE_EDGE_RISING>,
                 <SOC_PERIPHERAL_IRQ(138) IRQ_TYPE_EDGE_RISING>,
                 <SOC_PERIPHERAL_IRQ(139) IRQ_TYPE_EDGE_RISING>,
                 <SOC_PERIPHERAL_IRQ(140) IRQ_TYPE_EDGE_RISING>;
    interrupt-names = "error",
                     "ch0", "ch1", "ch2", "ch3",
                     "ch4", "ch5", "ch6", "ch7",
                     "ch8", "ch9", "ch10", "ch11",
                     "ch12", "ch13", "ch14", "ch15";
    clocks = <&cpg CPG_MOD R9A07G043_DMAC_ACLK>,
             <&cpg CPG_MOD R9A07G043_DMAC_PCLK>;
    clock-names = "main", "register";
    power-domains = <&cpg>;
    resets = <&cpg R9A07G043_DMAC_ARESETN>,
             <&cpg R9A07G043_DMAC_RST_ASYNC>;
    reset-names = "arst", "rst_async";
    #dma-cells = <1>;
    dma-channels = <16>;
};

```

### 5.1.2 On RZ/V2N and RZ/G3E

Figure 5–2 shows details about the initial reference information for DMAC node of RZ/V2N

```

dmacl: dma-controller@14830000 {
    compatible = "renesas,r9a09g056-dmac";
    reg = <0 0x14830000 0 0x10000>;
    interrupts = <GIC_SPI 495 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 25 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 26 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 27 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 28 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 29 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 30 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 31 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 32 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 33 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 34 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 35 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 36 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 37 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 38 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 39 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 40 IRQ_TYPE_EDGE_RISING>;
    interrupt-names = "error",
                    "ch0", "ch1", "ch2", "ch3",
                    "ch4", "ch5", "ch6", "ch7",
                    "ch8", "ch9", "ch10", "ch11",
                    "ch12", "ch13", "ch14", "ch15";
    clocks = <&cpg CPG_MOD 0x1>;
    power-domains = <&cpg>;
    resets = <&cpg 0x32>;
    #dma-cells = <1>;
    dma-channels = <16>;
    peripheral-request = <&icu 0>;
    status = "okay";
};

```

**Figure 5–2 Example of device tree of DMAC on RZ/V2N**

**Note:** Figure 5–2 shows an example of device tree settings of DMAC for RZ/V2N. Please use corresponding properties as noted below.

Required properties:

- **compatible:**  
must be "renesas, r9a09g056-dmac" for RZ/V2N  
must be "renesas, r9a09g047-dmac" for RZ/G3E
- **reg:**  
need two resources, first one mapped to register base address, second one mapped to extension resource registers base address.
- **interrupts:**  
interrupt specifier for the DMAC, one for each channel.
- **interrupt-names:**  
mapped with interrupts and must be in format: "error", "ch%u" (%u: channel number 0->15).



- dma-channels:  
number of dma channel. Maximum is 16.
- #dma-cells:  
must be 1.
- clocks, resets: phandle + clock/reset specifier pairs.  
0x32 is used for RZ/V2N.
- peripheral-request:  
The number icu specify for dmac, user can check **DMACx Factor Selection Register y (DMxSELy)**  
**(x = 0 to 4, y = 0 to 7)** of hardware manual for this number.  
Ex:       dmac1: <&icu 0>  
          dmac2: <&icu 1>

## 5.2 DMA setting for client

### 5.2.1 On RZ/G2L, RZ/G2LC, RZ/G2UL, RZ/V2L, and RZ/Five

```

ssi0: ssi@10049c00 {
    compatible = "renesas,r9a07g044-ssi",
                "renesas,rz-ssi";
    reg = <0 0x10049c00 0 0x400>;
    interrupts = <GIC_SPI 326 IRQ_TYPE_LEVEL_HIGH>,
                <GIC_SPI 327 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 328 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 329 IRQ_TYPE_EDGE_RISING>;
    interrupt-names = "int_req", "dma_rx", "dma_tx", "dma_rt";
    clocks = <&cpg CPG_MOD R9A07G044_SSI0_PCLK2>,
            <&cpg CPG_MOD R9A07G044_SSI0_PCLK_SFR>,
            <&audio_clk1>, <&audio_clk2>;
    clock-names = "ssi", "ssi_sfr", "audio_clk1", "audio_clk2";
    resets = <&cpg R9A07G044_SSI0_RST_M2_REG>;
    dmas = <&dmac 0x2655>, <&dmac 0x2656>;
    dma-names = "tx", "rx";
    power-domains = <&cpg>;
    #sound-dai-cells = <0>;
    status = "disabled";
};

spi1: spi@1004b000 {
    compatible = "renesas,r9a07g044-rspi", "renesas,rspi-rz";
    reg = <0 0x1004b000 0 0x400>;
    interrupts = <GIC_SPI 418 IRQ_TYPE_LEVEL_HIGH>,
                <GIC_SPI 416 IRQ_TYPE_LEVEL_HIGH>,
                <GIC_SPI 417 IRQ_TYPE_LEVEL_HIGH>;
    interrupt-names = "error", "rx", "tx";
    clocks = <&cpg CPG_MOD R9A07G044_RSPI1_CLKB>;
    resets = <&cpg R9A07G044_RSPI1_RST>;
    dmas = <&dmac 0x2e99>, <&dmac 0x2e9a>;
    dma-names = "tx", "rx";
    power-domains = <&cpg>;
    num-cs = <1>;
    #address-cells = <1>;
    #size-cells = <0>;
    status = "disabled";
};

```

**Figure 5–3 Device tree setting references for SSI and RSPI (RZ/G2L, RZ/V2L, and RZ/Five)**

In the client driver node:

```

dmas = <&dmac 0x2e99>, <&dmac 0x2e9a>;
dma-names = "tx", "rx";

```

With:

dmas specifies the encoded MID/RID values of the DMAC port connected to the DMA client and the slave channel configuration parameters.

- bits[0:9] - Specifies MID/RID value
- bit[10] - Specifies DMA request high enable (HIEN)
- bit[11] - Specifies DMA request detection type (LVL)
- bits[12:14] - Specifies DMAACK output mode (AM)
- bit[15] - Specifies Transfer Mode (TM)

dma-name name of dmac channel

- tx - dma transfer channel
- rx - dma receive channel

Please follow guideline in Documentation/devicetree/bindings/dma/renesas,rz-dmac.yaml

## 5.2.2 On RZ/V2N and RZ/G3E

```

spi2: spi@12800800 {
    compatible = "renesas,rspi-v2n";
    reg = <0 0x12800800 0 0x400>;
    interrupts = <GIC_SPI 112 IRQ_TYPE_LEVEL_HIGH>,
                <GIC_SPI 504 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 505 IRQ_TYPE_EDGE_RISING>;
    interrupt-names = "error", "rx", "tx";
    clocks = <&cpg CPG_MOD 0x5a>,
            <&cpg CPG_MOD 0x5b>,
            <&cpg CPG_MOD 0x5c>;
    resets = <&cpg 0x7f>;
    dmas = <&dmac1 0x7F4491>, <&dmac1 0x7F4490>;
    dma-names = "tx", "rx";
    power-domains = <&cpg>;
    num-cs = <1>;
    #address-cells = <1>;
    #size-cells = <0>;
    status = "disabled";
};

```

Figure 5–4 Device tree setting references for RSPI2 on RZ/V2N

```

spi0: spi@12800000 {
    compatible = "renesas,rspi-g3e";
    reg = <0 0x12800000 0 0x400>;
    interrupts = <GIC_SPI 106 IRQ_TYPE_LEVEL_HIGH>,
                <GIC_SPI 107 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 500 IRQ_TYPE_EDGE_RISING>,
                <GIC_SPI 501 IRQ_TYPE_EDGE_RISING>;
    interrupt-names = "error", "cend", "rx", "tx";
    clocks = <&cpg CPG_MOD 84>,
            <&cpg CPG_MOD 85>,
            <&cpg CPG_MOD 86>;
    clock-names = "pclk", "pclk_sfr", "tclk";
    resets = <&cpg 123>,
            <&cpg 124>;
    reset-names = "presetn", "tresetn";
    dmas = <&dmac1 0x7F448D>, <&dmac1 0x7F448C>;
    dma-names = "tx", "rx";
    power-domains = <&cpg>;
    num-cs = <1>;
    #address-cells = <1>;
    #size-cells = <0>;
    status = "disabled";
};

```

Figure 5–5 Device tree setting references for RSPI0 on RZ/G3E

RZ/V2N required the properties as below for the dma client:

```
dmac = <&dmac1 0x7F4491>, <&dmac1 0x7F4490>;  
dma-names = "tx", "rx";
```

RZ/G3E required the properties as below for the dma client:

```
dmac = <&dmac1 0x7F448D>, <&dmac1 0x7F448C>;  
dma-names = "tx", "rx";
```

Where:

dmac specifies the DMAC REQ values of the DMAC channel configuration connected to ICU parameters.

- bits[0:9] - Specifies DMAC request number value
- bit[10] - Specifies DMA request high enable (HIEN)
- bit[11] - Specifies DMA request detection type (LVL)
- bits[12:14] - Specifies DMAACK output mode (AM)
- bit[15] - Specifies Transfer Mode (TM)
- bits[22:16] - Specifies DMAACK output number : if not use define as 7F (all 1)

dma-name of dmac channel

- tx - dma transfer channel
- rx - dma receive channel

Please follow guidelines in Documentation/devicetree/bindings/dma/renesas,rz-dmac.yaml

## 6. Notes

### 6.1 Configuration for DMA Mem to Mem transaction.

For DMA mem to mem transaction, we need to care about the transfer data size (destination/source) and data alignment of the transaction.

Currently, in theory, DMAC can support up to **1024** bits transfer data size based on Hardware Manual.

**Table 6-1 Channel Configuration Register n/nS (CHCFG\_n/nS):**

Bit	Bit Name	Description																														
19 to 16	DDS [3:0]	Destination Data Size																														
		Sets the DMA transfer size of the transfer destination:																														
		<table><tr><th>Value</th><th>Size</th><th>Data Alignment</th></tr><tr><td>0000</td><td>8 bits</td><td>1 byte</td></tr><tr><td>0001</td><td>16 bits</td><td>2 bytes</td></tr><tr><td>0010</td><td>32 bits</td><td>4 bytes</td></tr><tr><td>0011</td><td>64 bits</td><td>8 bytes</td></tr><tr><td>0100</td><td>128 bits</td><td>16 bytes</td></tr><tr><td>0101</td><td>256 bits</td><td>32 bytes</td></tr><tr><td>0110</td><td>512 bits</td><td>64 bytes</td></tr><tr><td>0110</td><td>1024 bits</td><td>128 bytes</td></tr><tr><td>Other than the above</td><td>-</td><td>Setting prohibited</td></tr></table>	Value	Size	Data Alignment	0000	8 bits	1 byte	0001	16 bits	2 bytes	0010	32 bits	4 bytes	0011	64 bits	8 bytes	0100	128 bits	16 bytes	0101	256 bits	32 bytes	0110	512 bits	64 bytes	0110	1024 bits	128 bytes	Other than the above	-	Setting prohibited
		Value	Size	Data Alignment																												
		0000	8 bits	1 byte																												
		0001	16 bits	2 bytes																												
		0010	32 bits	4 bytes																												
		0011	64 bits	8 bytes																												
		0100	128 bits	16 bytes																												
		0101	256 bits	32 bytes																												
		0110	512 bits	64 bytes																												
		0110	1024 bits	128 bytes																												
Other than the above	-	Setting prohibited																														
15 to 12	SDS [3:0]	Source Data Size																														
		Sets the DMA transfer size of the transfer source:																														
		<table><tr><th>Value</th><th>Size</th><th>Data Alignment</th></tr><tr><td>0000</td><td>8 bits</td><td>1 byte</td></tr><tr><td>0001</td><td>16 bits</td><td>2 bytes</td></tr><tr><td>0010</td><td>32 bits</td><td>4 bytes</td></tr><tr><td>0011</td><td>64 bits</td><td>8 bytes</td></tr><tr><td>0100</td><td>128 bits</td><td>16 bytes</td></tr><tr><td>0101</td><td>256 bits</td><td>32 bytes</td></tr></table>	Value	Size	Data Alignment	0000	8 bits	1 byte	0001	16 bits	2 bytes	0010	32 bits	4 bytes	0011	64 bits	8 bytes	0100	128 bits	16 bytes	0101	256 bits	32 bytes									
		Value	Size	Data Alignment																												
		0000	8 bits	1 byte																												
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		0011	64 bits	8 bytes																												
		0100	128 bits	16 bytes																												
0101	256 bits	32 bytes																														

		0110	512 bits	64 bytes
		0110	1024 bits	128 bytes
		Other than the above	-	Setting prohibited

Currently, in Linux driver (**drivers/dma/sh/rz-dmac.c**), the DMA transfer size for destination and source are set to 8 bits via **CHCFG\_MEM\_COPY** macro.

```
#define CHCFG_MEM_COPY (0x80400008)
```

This default setting can cause low performance when doing the DMA mem-to-mem transaction.

To increase the transfer speed, please change the value of this macro to your considered DMA transfer size (compatible with data alignment) based on the above table.

Example: set the DMA transfer size to 32 bits

```
#define CHCFG_MEM_COPY (0x80422008)
```

Below is the experimental DMA mem to mem transfer speed for 16MB data on RZ/G2L Smarc Board.

Transfer data size (bits)	Average Time (ms)	Average Transfer Speed (KB/s)
8	7220	2269
16	3610	4537
32	1807	9064
64	905	18092
128	415	39464
256	229	71410
512	130	125450
1024	80	203996

Revision History	Linux Interface Specification Device Driver DMAC User's Manual: Software
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Rev.	Date	Description	
		Page	Summary
0.50	Apr. 30, 21	—	First Edition issued
1.0	Jul. 15, 2021	—	No modification, keep version to keep consistent with other documents
1.1	Sep. 15, 2021	—	Merge RZ/G2L driver manual with RZ/V2L
1.2	Feb. 15, 2022	—	Add RZ/G2UL, RZ/G2LC device
1.3	Mar. 31, 2022	—	Change to rz-dmac driver when moving to kernel 5.10
1.4	May. 31, 2022	—	Update version and add RZ/V2L
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1.9	Jul. 31, 2024	10, 11	Add note about DMA mem to mem transaction
1.10	Mar. 31, 2025	1, 4, 7, 8	Correct device tree node for RZ/G2L series, RZ/V2L and RZ/Five, correct DMA function and update DMA Engine Driver configuration
1.11	May. 30, 2025	1	Add MPU information support for both kernel versions v5.10 and v6.1.
1.12	Jun. 30, 2025	—	Merge the document with RZ/V2N document
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